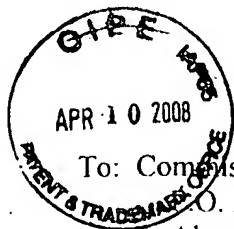


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Apr. 2, 2008

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/786,807 02/25/2004

H. M. CHEN

"METHOD FOR IMPROVING SEMICONDUCTOR
WAFER TEST ACCURACY"

Grp. Art Unit: 2822

AU, BACH

RESPONSE TO FINAL OFFICE ACTION

Dear Sir:

In response to the Non-Final Office Action mailed Oct. 5, 2007, please amend the above-identified application for patent and consider the remarks, as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on Apr. 7, 2008.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date

April 7, 2008